

Amendments to the Specification

Please amend the paragraph **(previously added by the Amendment and Response dated January 9, 2003)** at page 7, line 20 in the Brief Description of the Drawings to read as follows:

--Fig. 4 is a cross-sectional drawing that shows the general construction of an example of the first embodiment of an electronic device according to the present invention, ~~(A) being a cross-section view thereof, and (B) being a cross-section view thereof, as seen from the direction indicated by the arrows along the line 4B shown in (A).~~--

Please replace the paragraph beginning at page 8, line 35 **(previously added by the Amendment and Response dated January 9, 2003)** with the following rewritten paragraph:

--The position of the sealing resin injection port 90 in this embodiment, as shown by the double-dot-dash line in Fig. 1, and as shown in Fig. 4 ~~Figures 4A and 4B~~, is preferably on a longer side of the package, offset from the center thereof towards one of the shorter sides, avoiding the bonding wires 50, with sealing resin being injected therethrough in the direction shown by the arrow 93 in Fig. 1 ~~and by direction arrow 93 in Fig. 4B~~, in order to prevent the bonding wires 50 from toppling by injection pressure of the sealing resin acting on the side surfaces of the bonding wires 50 directly. By making the resin package small, it would be difficult as done in the past to provide a resin injection port on a shorter side of the package. Additionally, because the spacing between the inner wall of the resin die, shown in Fig. 4 ~~Figs. 4A and 4B~~ as upper die 91 and lower die 92, and the inner lead becomes narrow, it would be difficult to cause resin to sufficiently fill in under the inner lead. For this reason, by injecting

sealing resin, as noted above, from a longer side at a position that is offset toward one of the shorter sides of the package, the resin fills into the die smoothly, thereby preventing problems with insufficient resin filling.--